



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)}	Ι _D T _C = +25°C
950V	2.2Ω@V _{GS} = 10V	6A

Description

This new generation complementary dual MOSFET features low onresistance and fast switching, making it ideal for high efficiency power management applications.

Applications

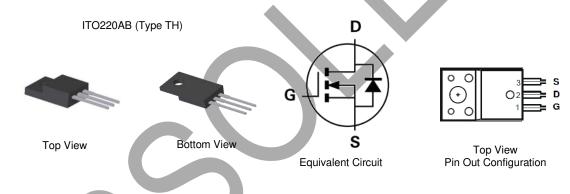
- Motor controls
- Backlighting
- DC-DC converters
- Power management functions

Features

- Low Input Capacitance
- High BVDSS Rating for Power Application
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

Mechanical Data

- Package: ITO220AB
- Package Material: Molded Plastic, "Green" Molding Compound, UL Flammability Classification Rating 94V-0
- Terminals: Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram Below
- Weight: 1.85 grams (Approximate)



Ordering Information (Note 4)

Part Number	Baakaga		Packing		
		Package	Qty.	Carrier	
DMN95H2D2HCTI	ITO	220AB (Type TH)	50 Pieces	Tube	

Notes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	950	V
Gate-Source Voltage		Vgss	±30	V
Continuous Drain Current (Note 5) V _{GS} = 10V	Tc = +25°C T _C = +100°C	ID	6 4	А
Pulsed Drain Current (Note 6)		ldм	24	A
Avalanche Current, L = 60mH (Note 7)		las	3.5	A
Avalanche Energy, L = 60mH (Note 7)		Eas	360	mJ

Thermal Characteristics

Characteristic				Max	Unit
Power Dissipation (Note 5)	Tc = +25°C Tc = +100°C	PD		40 14	w
Thermal Resistance, Junction to Case (Note 5)	$T_C = +25^{\circ}C$	Rejc		3.6	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)	•,						
Drain-Source Breakdown Voltage	BV _{DSS}	950	_		V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS		—	1	μA	$V_{DS} = 950V, V_{GS} = 0V$	
Gate-Source Leakage	GSS		—	100	nA	$V_{GS} = \pm 30V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	VGS(TH)	3	4	5	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
Static Drain-Source On-Resistance	RDS(ON)	—	1.7	2.2	Ω	$V_{GS} = 10V, I_D = 3A$	
Diode Forward Voltage	Vsd	-	0.85	1.2	V	$V_{GS} = 0V$, $I_S = 6A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	Ciss		1487	_			
Output Capacitance	Coss		113	_	pF	$V_{DS} = 25V, f = 1MHz,$ $V_{GS} = 0V$	
Reverse Transfer Capacitance	Crss	_	1	_		VGS = 0V	
Gate Resistance	Rg	_	4.7	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge	Qg	_	20.3	_		$\label{eq:VDD} \begin{split} V_{DD} &= 720V, \ I_D = 6A, \\ V_{GS} &= 10V \end{split}$	
Gate-Source Charge	Qgs	_	6.4		nC		
Gate-Drain Charge	Qgd	_	6.1	_			
Turn-On Delay Time	tD(ON)	_	39			V _{DD} = 450V, V _{GS} = 10V,	
Turn-On Rise Time	t _R	_	49		ns		
Turn-Off Delay Time	tD(OFF)	_	51	_	115	$R_g = 25\Omega, I_D = 6A$	
Turn-Off Fall Time	tF	_	31		1		
Body Diode Reverse Recovery Time	trr	—	607	_	ns		
Body Diode Reverse Recovery Charge	Q _{RR}	_	8.1	—	μC	I _F = 6A, dl/dt = 100A/µs	

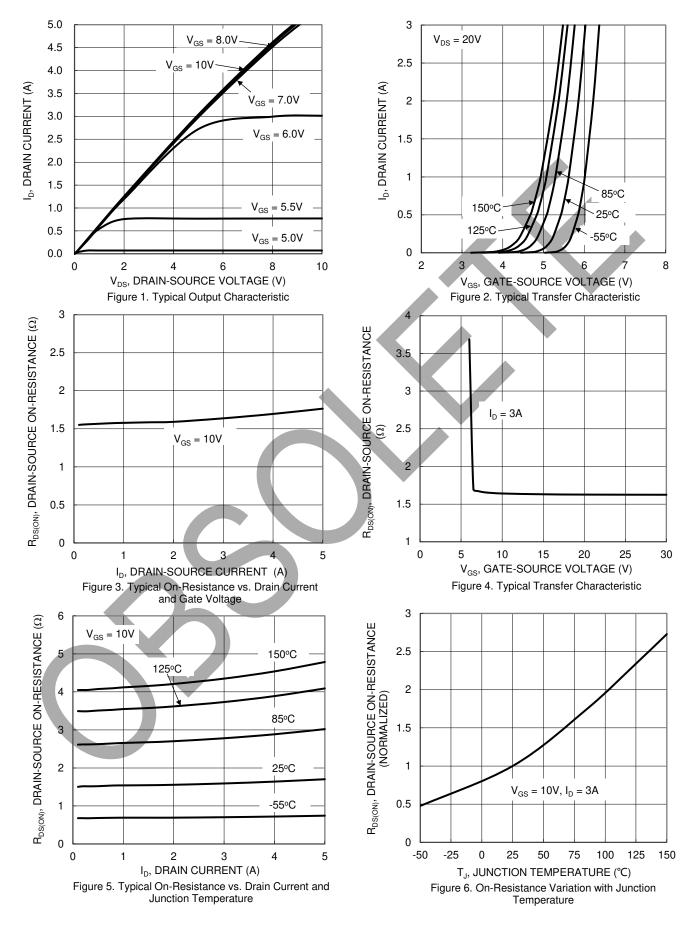
Notes:

Device mounted on infinite heatsink.
Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Guaranteed by design. Not subject to production testing.

8. Short duration pulse test used to minimize self-heating effect.



DMN95H2D2HCTI





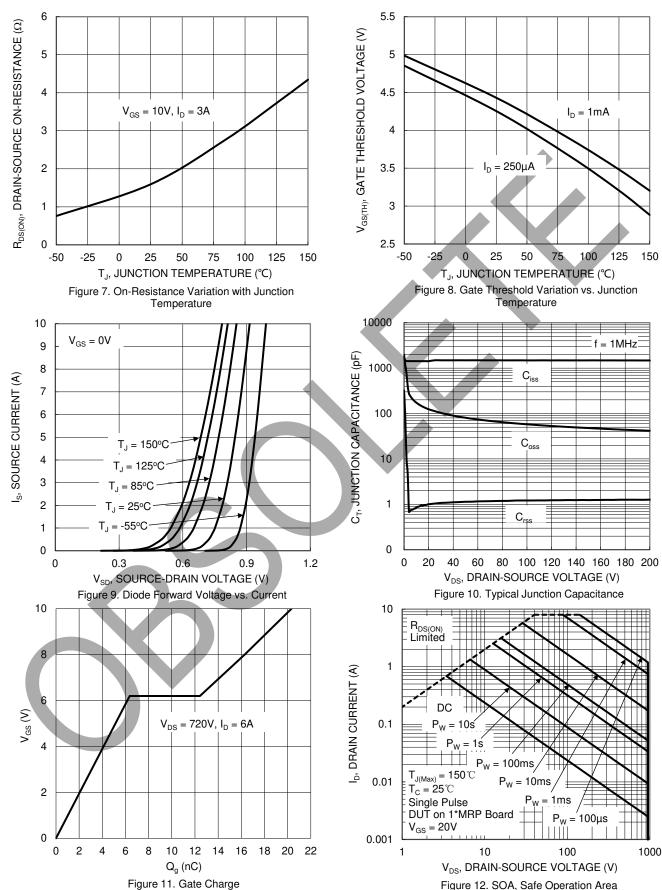
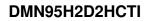
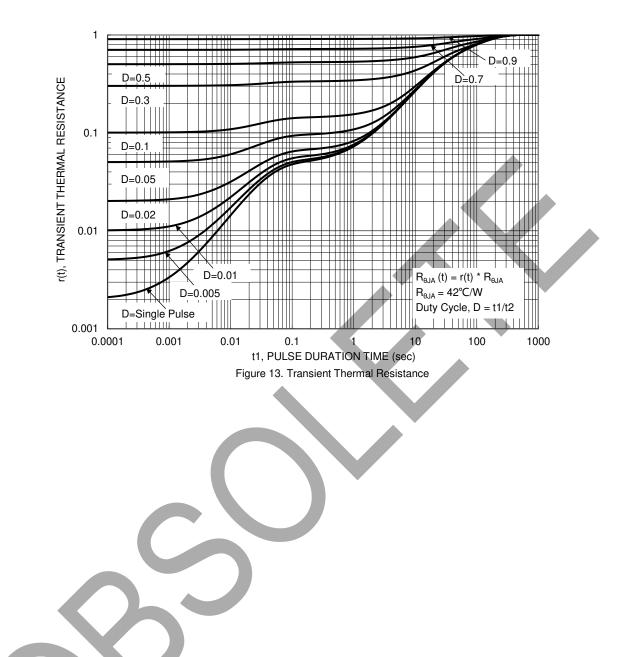


Figure 12. SOA, Safe Operation Area



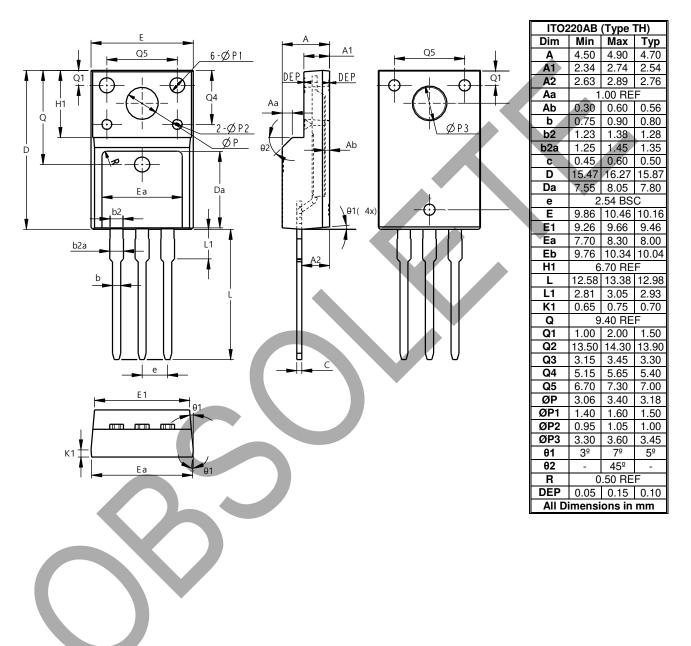






Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



ITO220AB (Type TH)



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